UTT60N03H-H

Preliminary

Power MOSFET

60A, 30V N-CHANNEL POWER MOSFET

■ DESCRIPTION

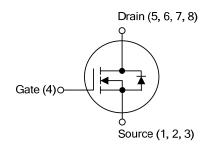
The UTC **UTT60N03H-H** is a N-channel Power MOSFET, it uses UTC's advanced technology to provide the customers with high switching speed, low C_{RSS} and low gate charge.

The UTC **UTT60N03H-H** is suitable for high power density DC/DC and embedded DC/DC applications.



- * $R_{DS(ON)}$ < 5.5m Ω @ V_{GS} =10V, I_{D} =10A $R_{DS(ON)}$ < 8.5m Ω @ V_{GS} =4.5, I_{D} =8A
- * High switching speed
- * Low C_{RSS}
- *Low gate change

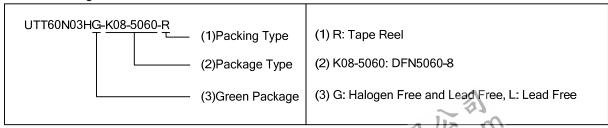
■ SYMBOL



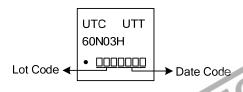
■ ORDERING INFORMATION

Ordering Number		Dookogo	Pin Assignment							Dooking	
Lead Free	Halogen Free	Package	1	2	3	4	5	6	7	8	Packing
UTT60N03HL-K08-5060-R	UTT60N03HG-K08-5060-R	DFN5060-8	S	S	S	G	D	D	D	D	Tape Reel
N. C.											

Note: Pin Assignment: G: Gate D: Drain S: Source



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■ **ABSOLUTE MAXIMUM RATINGS** (T_A=25°C, unless otherwise specified)

			1			
PARAMETER			SYMBOL	RATINGS	UNIT	
Drain-Source Voltage			$V_{ extsf{DSS}}$	30	V	
Gate-Source Voltage		V_{GSS}	+20, -16	V		
Drain Current	Continuous	T _C =25°C	I_{D}	60 (Note 6)	Α	
(T _J =150°C)	Pulsed (t=300	us)	I _{DM}	80	Α	
Continuous Source-Drain Diode T _C =25°C			14.1 (Note 6)	_		
Current		T _A =25°C	- I _S	3.2 (Note 2, 3)	A	
Avalanche Current (L=0.1mH)		I _{AR}	15	Α		
Single Pulsed Avalanche Energy (L=0.1mH)		E _{AS}	11.25	mJ		
Power Dissipation T _C =25°C		P_D	31.2	W		
Junction Temperature		TJ	-55 ~ +150	°C		
Storage Temperature Range		T _{STG}	-55 ~ +150	°C		
Soldering Recommendations (Peak Temperature) (Note 4)			260	°C		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL CHARACTERISTICS

PARAMETER	_	SYMBOL	RATINGS	UNIT	
Junction to Ambient (Note 2, 5)	t≤10s	θ_{JA}	34	°C/W	
Junction to Case (Drain)	Steady State	θ_{JC}	4	°C/W	

Notes: 1. Based on T_C=25°C

- 2. Surface mounted on 1"x1" FR4 board.
- 3. t=10s
- 4. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- 5. Maximum under steady state conditions is 70°C/W
- 6. Package limited



ELECTRICAL CHARACTERISTICS (T_J=25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS									
Drain-Source Breakdown Voltag	е	BV _{DSS}	I _D =250μA, V _{GS} =0V	30			V		
V _{DS} Temperature Coefficient		$\triangle V_{DS}/T_{J}$	I _D =250uA		20		mV/°C		
V _{GS(TH)} Temperature Coefficient		$\triangle V_{GS(TH)}/T_J$	ID-250UA		-4.6		IIIV/ C		
Drain-Source Leakage Current		I _{DSS}	V_{DS} =30V, V_{GS} =0V			1	μA		
			V _{DS} =30V, V _{GS} =0V, T _J =55°C			10	μA		
Gate-Source Leakage Current	Forward	I _{GSS}	V_{GS} =+20V, V_{DS} =0V			+100	nA		
	Reverse	1688	V _{GS} =-16V, V _{DS} =0V			-100	nA		
ON CHARACTERISTICS									
Gate Threshold Voltage		V _{GS(TH)}	$V_{DS}=V_{GS}$, $I_D=250\mu A$	1.1		2.2	V		
Static Drain-Source On-State Re	esistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A			5.5	mΩ		
(Note 1)			V _{GS} =4.5V, I _D =8A			8.5	11122		
On State Drain Current		$I_{D(ON)}$	V _{DS} ≥5V, V _{GS} =10V	30			Α		
DYNAMIC PARAMETERS (Note	e 2)								
Input Capacitance		C _{ISS}			1450		pF		
Output Capacitance		Coss	V_{GS} =0V, V_{DS} =15V, f=1MHz		445		pF		
Reverse Transfer Capacitance		C _{RSS}			38		pF		
SWITCHING PARAMETERS									
Total Gate Charge		Q _G	V _{GS} =10V, V _{DS} =15V, I _D =10A		19.4	29	nC		
			V _{GS} =4.5V, V _{DS} =15V, I _D =10A		9.4	14	nC		
Gate to Source Charge		Q _{GS}	66 1 , 26 1 , 5		4				
Gate to Drain Charge		Q_{GD}			1.8		nC		
Gate Resistance		R _G	f=1MHz	0.4	1.65	3.3	Ω		
Turn-ON Delay Time		t _{D(ON)}			9	18	ns		
Rise Time		t _R	V _{DD} =15V, I _D ≈10A, R _L =1.5Ω,		8	16	ns		
Turn-OFF Delay Time		t _{D(OFF)}	V_{GEN} =10V, R_G =1 Ω		18	36	ns		
Fall-Time		t _F			8	16	ns		
Turn-ON Delay Time		t _{D(ON)}			15	30	ns		
Rise Time		t _R	V _{DD} =15V, I _D ≈10A, R _L =1.5Ω,		12	24	ns		
Turn-OFF Delay Time		t _{D(OFF)}	V_{GEN} =4.5V, R_{G} =1 Ω		18	36	ns		
Fall-Time		t_{F}			9	18	ns		
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS									
Maximum Body-Diode Continuo	us Current	Is	T _C =25°C			14.1	Α		
Maximum Body-Diode Pulsed Co	urrent	I _{SM}				80	Α		
(Note 1)									
Drain-Source Diode Forward Vo		V _{SD}	I _S =3A		0.76	1.1	V		
Body Diode Reverse Recovery 1		t _{rr}	_		24	48	ns		
Body Diode Reverse Recovery (Charge	Q _{rr}	I _F =10A, dI/dt=100A/μs,		14	28	nC		
Reverse Recovery Fall Time		ta	T _J =25°C		12		ns		
Reverse Recovery Rise Time		t _b			12		ns		

Notes: 1. Pulse test; pulse width ≤30µs, duty cycle ≤2%

2. Guaranteed by design, not subject to production testing



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